1,048,576 WORD × 4 BIT DYNAMIC RAM

PRELIMINARY

DESCRIPTION

The TC514410AP/AJ/ASJ/AZ is the new generation dynamic RAM organized 1,048,576 words by 4 bits. The TC514410AP/AJ/ASJ/AZ utilizes TOSHIBA's CMOS Silicon gate process technology as well as advanced circuit techniques to provide wide operating margins, both internally and to the system user. Multiplexed address inputs permit the TC514410AP/AJ/ASJ/AZ to be packaged in a standard 20 pin plastic DIP, 26/20 pin plastic SOJ (300/350mil) and 20 pin plastic ZIP. The package size provides high system bit densities and is compatible with widely available automated testing and insertion equipment. System oriented features include single power supply of 5V±10% tolerance, direct interfacing capability with high performace logic families such as Schottky TTL.

FEATURES

- 1,048,576 word by 4 bit organization
- · Fast access time and cycle time

	TC514410AP/A	1/AS]/ AZ - 7	70/ – 80/ – 10
t _{RAC} RAS Access Time	70ns	80ns	100ns
t _{AA} Column Address Access Time	35ns	40ns	50ns
t _{CAC} CAS Access Time	20ns	20ns	25ns
t _{RC} Cycle Time	130ns	150ns	180ns
t _{PC} Fast Page Mode Cycle Time	45ns	50ns	60ns

PIN NAMES

A0~A9	Address Inputs
RAS	Row Address Strobe
CAS	Column Address Strobe
WB/WE	Write Per Bit/Read/Write Input
<u>oe</u>	Output Enable
W1/101~W4/104	Write Select/Date Input/Output
Vcc	Power (+ 5V)
Vss	Ground

PIN CONNECTION (TOP VIEW)

Plast	ic DIP	Plasti	c SOJ	Pla	stic ZIP
W1/IO1[1 W2/IO2[2] WB/WE[3] RAS[4 A9[5] A0[6 A1[7 A2[8 A3[9 Vcc[10	201Vss 191W4/104 181W3/103 171CAS 161OE 151A8 141A7 131A6 121AS 111A4		26 Vss W4/104 24 W3/103 22 DOE 3 DOE 18 JA8 17 JA7 16 JA6 15 JA5 14 JA4	OE W3/103 3 Vss W2/102 7 RAS A0 A2 Vsc A5 A7	7 CAS W4/104 16 W1/101 18 WEAVE 100 A9 117 A1 12 (14 A3 13 (16 A4 17 (18 A5 19 (10 A8

Single power supply of 5V±10% with a built-in VBB generator

Low Power 550mW MAX. Operating (TC514410AP/AJ/ASJ/AZ-70) 468mW MAX. Operating (TC514410AP/AJ/ASJ/AZ-80) 413mW MAX. Operating (TC514410AP/AJ/ASJ/AZ-10) 5.5mW MAX. Standby

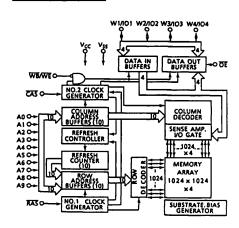
Output unlatched at cycle end allows

Output uniatched at cycle end allows two-dimensional chip selection Read-Modify-Write, CAS before RAS refresh, RAS-only refresh, Hidden refresh, Write per Bit, Fast Page Mode and Test Mode capability All inputs and outputs TTL Compatible

1024 refresh cycles/16ms

Package TC514410AP : DIP20-P-300C TC514410AJ : SOJ26-P-350 TC514410ASJ : SOJ26-P-300A TC514410AZ : ZIP2-P-400A

BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS

ITEM	SYMBOL	RATING	UNITS	NOTES
Input Voltage	V _{IN}	- 1~7	٧	1
Output Voltage	Vout	- 1~7	٧	1
Power Supply Voltage	Vcc	- 1~7	v	1
Operating Temperature	T _{OPR}	0~70	*c	1
Storage Temperature	T _{STG}	- 55~150	•c	1
Soldering Temperature · Time	TSOLDER	260 · 10	*C · sec	1
Power Dissipation	Po	700	mW	1
Short Circuit Output Current	lout	50	mA	1

RECOMMENDED DC OPERATING CONDITIONS (Ta = 0~70°c)

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT	NOTES
Vcc	Supply Voltage	4.5	5.0	5.5	٧	2
VIH	Input High Voltage	2.4	•	6.5	V	2
VIL	Input Low Voltage	- 1.0	-	0.8	V	2

DC ELECTRICAL CHARACTERISTICS ($V_{CC} = 5V \pm 10\%$, Ta = 0~70°c)

SYMBOL	PARAMETER		MIN.	MAX.	UNITS	NOTES
	OPERATING CURRENT	TC514410AP/AJ/ASJ/AZ-70		100		3, 4
l _{CC1}	Average Power Supply Operating Current	TC514410AP/AJ/ASJ/AZ-80	-	85	mA	· 1
	(RAS, CAS, Address Cycling: t _{RC} = t _{RC} MIN.)	TC514410AP/AJ/ASJ/AZ-10		75		5
l _{CC2}	STANDBY CURRENT Power Supply Standby Current (RAS = CAS = V _{IH})		-	2	mA	
	RAS ONLY REFRESH CURRENT	TC514410AP/AJ/ASJ/AZ-70	-	100		
l _{CC3}	Average Power Supply Current, RAS Only Mode	TC514410AP/AJ/ASJ/AZ-80		85	mA	3, 5
	(RAS Cycling, CAS = VIH: tRC = tRC MIN.)	TC514410AP/AJ/ASJ/AZ-10		75	ļ	
	FAST PAGE MODE CURRENT	TC514410AP/AJ/ASJ/AZ-70	-	70		3, 4
	Average Power Supply Current, Fast Page Mode	TC514410AP/AJ/ASJ/AZ-80	•	65	mA.	'
I _{CC4}	(RAS = V _{IL} , CAS, Address Cycling: t _{PC} = t _{PC} MIN.)	TC514410AP/AJ/ASJ/AZ-10	-	55		5
I _{ccs}	STANDBY CURRENT Power Supply Standby Current (RAS = CAS = V _{CC} = 0.2V)		-	1	mA	
	CAS BEFORE RAS REFRESH CURRENT	TC514410AP/AJ/ASJ/AZ-70	-	100		
1 _{CC6}	Average Power Supply Current, CAS Before RAS	TC514410AP/AJ/ASJ/AZ-80	_	85	mA	3, 5
1	Mode (RAS, CAS Cycling: t _{RC} ≠ t _{RC} MIN.)	TC514410AP/AJ/ASJ/AZ-10	-	75	1	
lι(u)	INPUT LEAKAGE CURRENT Input Leakage Current, any input $(0V \le V_{IN} \le 6.5V$, All Other Pins not under Test = 0	n	- 10	10	μА	
lo (L)	OUTPUT LEAKAGE CURRENT (D _{OUT} is disabled, 0V≤V _{OUT} ≤5.5V)		- 10	10	μА	
Voн	OUTPUT LEVEL Output "H" Level Voltage (I _{OUT} = -5mA)		2.4	-	v	
VoL	OUTPUT LEVEL Output "L" Level Voltage (I _{OUT} = 4.2mA)		_	0.4	v	



ELECTRICAL CHARACTERISTICS AND RECOMMENDED AC OPERATING CONDITIONS

 $(V_{CC} = 5V \pm 10\%, Ta = 0 \sim 70^{\circ}c)$ (Notes 6, 7, 8)

SYMBOL	PARAMETER		4410AP/ SJ/AZ-70		4410AP/ SJ/AZ-80		4410AP/ SJ/AZ-10	UNIT	NOTES
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
t _{RC}	Random Read or Write Cycle Time	130	-	150	. 1	180	1	ns	
t _{RMW}	Read-Modify-Write Cycle Time	185	-	205	-	245	1	ns	
t _{PC}	Fast Page Mode Cycle Time	45	1	50	•	60	•	ns	
t _{PRMW}	Fast Page Mode Read-Modify-Write Cycle Time	100	-	105		125	<u> </u>	ns	
trac	Access Time from RAS	-	70	-	80	-	100	ns	9,14 15
tCAC	Access Time from CAS	-	20	1	20	1	25	ns	9,14
taa	Access Time from Column Address	-	35	-	40	-	50	ns	9,15
t _{CPA}	Access Time from CAS Precharge	-	40	•	45		55	ns	9
^t CLZ	CAS to output in Low-Z	0	-	0	-	0	-	ns	9
toff	Output Buffer Turn-off Delay	0	20	0	· 20	0	20	ns	10
t _T	Transition Time (Rise and Fall)	3	50	3	50	3	50	ns	8
t _{RP}	RAS Precharge Time	50	-	60	-	70	-	ns	
t _{RAS}	RAS Pulse Width	70	10,000	80	10,000	100	10,000	ns	
trasp	RAS Pulse Width (Fast Page Mode)	70	200,000	80	200,000	100	200,000	ns	
t _{RSH}	RAS Hold Time	20	-	20	-	25	_	ns	
t _{RHCP}	RAS Hold Time From CAS Precharge (Fast Page Mode)	40	-	45	-	55	-	ns	
tcsH	CAS Hold Time	70	-	80	-	100	•	ns	
t _{CAS}	CAS Pulse Width	20	10,000	20	10,000	25	10,000	ns	
t _{RCD}	RAS to CAS Delay Time	20	. 50	20	60	25	75	ns	14
tRAD	RAS to Column Address Delay Time	15	35	15	40	20	50	ns	15
t _{CRP}	CAS to RAS Precharge Time	5	-	5	-	10	•	ns	
t _{CP}	CAS Precharge Time	10	-	10		10	1	ns	
tasr	Row Address Set-Up Time	0	-	0	-	0	-	ns	
t _{RAH}	Row Address Hold Time	10		10	-	15	-	ns	
tasc	Column Address Set-Up Time	0	-	0	-	0	-	ns	
t _{CAH}	Column Address Hold Time	15	-	15	-	20	-	ns	
tRAL	Column Address to RAS Lead Time	35	-	40	-	50	_	ns	
t _{RCS}	Read Command Set-Up Time	_ 0	_	0	_	0	-	ns	
t _{RCH}	Read Command Hold Time	0	_	0	_	0	_	ns	11

ELECTRICAL CHARACTERISTICS AND RECOMMENDED AC OPERATING CONDITIONS (Continued)

SYMBOL	PARAMETER		4410AP/ SJ/AZ-70		4410AP/ 5J/AZ-80		4410AP/ 5J/AZ-10	UNITS	NOTES
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
t _{RRH}	Read Command Hold Time referenced to RAS	0	-	0	_	0	-	ns	11
twcH	Write Command Hold Time	- 15	-	15		20		ns	
t _{WP}	Write Command Pulse Width	15	1	15		20	-	ns	
tRWL	Write Command to RAS Lead Time	20	1	20	-	25	•	ns	
[‡] CWL	Write Command to CAS Lead Time	20		20	-	25	-	ns	
tos	Data Set-Up Time	0	-	0	-	0	-	ns	12
t _{DH}	Data Hold Time	15	-	15	-	20	-	ns	12
tREF	Refresh Period	-	16	-	16	-	16	ms	
twcs	Write Command Set-UP Time	0	-	0	-	0	-	ns	13
tcwo	CAS to WE Delay Time	50	-	50	_·	60	_	ns	13
t _{RWD}	RAS to WE Delay Time	100	-	110	-	135	-	ns	13
tawo	Column Address to WE Delay Time	65	-	70	•	85		ns	13
icewo	CAS Precharge to WRITE Delay Time	75	-	75	-	90	-	ns	13
t _{CSR}	CAS Set-Up Time (CAS before RAS Cycle)	5	-	5	-	5	-	ns	
t _{CHR}	CAS Hold Time (CAS before RAS Cycle)	15	-	15	-	20	-	ns	
t _{RPC}	RAS to CAS Precharge Time	0	-	0	-	0	-	ns	
t _{СРТ}	CAS Precharge Time (CAS before RAS Counter Test Cycle)	40	_	40	-	50	-	ns	
t _{ROH}	RAS Hold Time referenced to OE	10	-	10	-	20	~	ns	
toea	OE Access Time	T-	20	-	20	-	25	ns	
tOED	OE to Data Delay	20	_	20	-	25	-	ns	
t _{OEZ}	Output buffer turn off Delay Time from OE	0	20	0	20	0	20	ns	
t _{OEH}	OE Command Hold Time	20	-	20	-	25	-	ns	T
twas	Write Per Bit Set-Up Time	0	-	0	-	0	-	ns	T^{-}
twen	Write Per Bit Hold Time	10	-	10	-	10	-	ns	T
t _{WDS}	Write Per Bit Selection Set-Up Time	0	-	0	-	0	-	ns	T
twon	Write Per Bit Selection Hold Time	10	-	10		10	-	ns	T



ELECTRICAL CHARACTERISTICS AND RECOMMENDED AC OPERATING CONDITIONS (Continued)

SYMBOL	PARAMETER				4410AP/ SJ/AZ-10	UNIT	NOTES		
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	1.	
twrs	Write Command Set-up Time	10		10	-	10		ns	
twTH	Write Command Hold Width	10	1	10		10	-	ns	
twrp	WE to RAS Precharge Time	10	-	10	-	10	-	ns	
twrH	WE to RAS Hold Time	10	-	10	-	10		ns	

ELECTRICAL CHARACTERISTICS AND RECOMMENDED AC OPERATING CONDITIONS IN THE TEST MODE $(V_{CC} = 5V \pm 10\%, Ta = 0 \sim 70^{\circ}c)$ (Notes 6, 7, 8)

SYMBOL	PARAMETER		4410AP/ 5J/AZ-70		4410AP/ SJ/AZ-80		4410AP/ SJ/AZ-10	UNIT	NOTES
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	Ĺ	<u> </u>
t _{RC}	Random Read or Write Cycle Time	135	_	155		185	-	ns	
t _{RMW}	Read-Modify-Write Cycle Time	160	-	180	-	215	1	ns	
t _{PC}	Fast Page Mode Cycle Time	50		55	1	65	-	ns	
tpRMW	Fast Page Mode Read-Modify-Write Cycle Time	75		80	-	. 95	-	ns	
trac	Access Time from RAS	_	75	. •	85	1	105	ns	9,14, 15
t _{CAC}	Access Time from CAS	_	25	1,	25		30	ns	9,14
taa	Access Time from Column Address		40	1	45		55	ns	9,15
t _{CPA}	Access Time from CAS Precharge	-	45	-	50	•	60	ns	9
t _{RAS}	RAS Pulse Width	75	10,000	85	10,000	105	10,000	ns	
tRASP	RAS Pulse Width (Fast Page Mode)	75	200,000	85	200,000	105	200,000	ns	
t _{RSH}	RAS Hold Time	25	-	25		30	-	ns	
^t CSH	CAS Hold Time	75	-	85	-	105	+	ns	
t _{RHCP}	CAS Precharge to RAS Hold Time	45	_	50		60	-	ns	
t _{CAS}	CAS Pulse Width	25	10,000	25	10,000	30	10,000	ns	
tRAL	Column Address to RAS Lead Time	40	-	45	-	55		ns	
t _{CWD}	CAS to WE Delay Time	55	•	55		65	-	ns	13
t _{RWD}	RAS to WE Delay Time	105	-	115	-	140	-	ns	13
t _{AWD}	Column Address to WE Delay Time	70		75	-	90	_	ns	13
t _{CPWD}	CAS Precharge to WRITE Delay Time	80	_	80	-	95	-	ns	13
^t OEA	OE Access Time	-	25	-	25	-	30	ns	
t _{OEH}	OE Command Hold Time	25	-	25	-	30	-	ns	

CAPACITANCE ($V_{CC} = 5V \pm 10\%$, f = 1MHz, $Ta = 0 \sim 70$ °c)

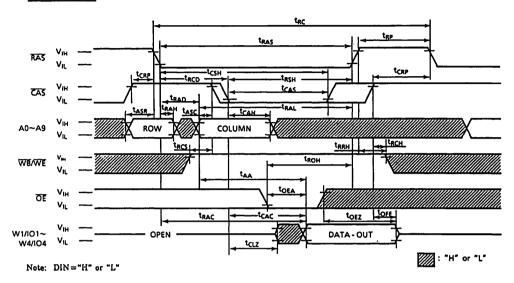
SYMBOL	PARAMETER	MIN.	MAX.	UNIT
C _{I1}	Input Capacitance (A0~A9)	-	5	pF
C _{I2}	Input Capacitance (RAS, CAS, W8/WE, OE)	-	7	pF
c _o	Input/Output Capacitance (I/I01~I/I04)	-	7	pF



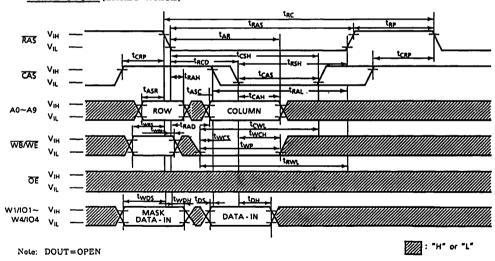
NOTES:

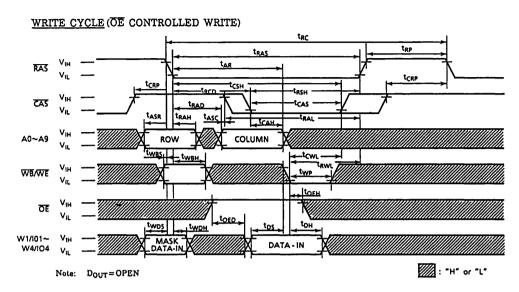
- Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device.
- 2. All voltages are referenced to VSS.
- 3. ICC1, ICC3, ICC4, ICC6 depend on cycle rate.
- 4. ICC1, ICC4 depend on output loading. Specified values are obtained with the output open.
- 5. Column address can be changed once or less while RAS=VIL and CAS=VIH.
- 6. An initial pause of 200µs is required after power-up followed by 8 RAS only refresh before proper device operation is achieved. In case of using internal refresh counter, a minimum of 8 CAS before RAS refresh cycles instead of 8 RAS refresh cycles are required.
- 7. AC measurements assume tr=5ns.
- V_{III} (min.) and V_{IL} (max.) are reference levels for measuring timing of input signals. Also, transition times are measured between V_{III} and V_{IL}.
- 9. Measured with a load equivalent to 2 TTL loads and 100pF.
- 10. toff (max.) and defines the time at which the output achieves the open circuit condition and is not referenced to output voltage levels.
- 11. Either tRCH or tRRH must be satisfied for a read cycle.
- 12. These parameters are referenced to CAS leading edge in early write cycles and to WRITE leading edge in Read-Write cycles.
- 13. twcs, trwd, tcwd, tawd and tcpwd are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only. If twcs≥twcs (min.), the cycle is an early write cycle and the data out pin will remain open circuit (high impedance) throughout the entire cycle; If trwd≥trwd (min.), tcwd≥tcwd (min.), tawd≥tawd (min.) and tcpwd≥tcpwd (min.) (Fast Page Mode), the cycle is a Read-Write cycle and the data out will contain data read from the selected cell: If neither of the above sets of conditions is satisfied, the condition of the data out (at access time) is indeterminate.
- 14. Operation within the t_{RCD} (max.) limit insures that t_{RAC} (max.) can be met. t_{RCD} (max.) is specified as a reference point only: If t_{RCD} is greater than the specified t_{RCD} (max.) limit, then access time is controlled by t_{CAC}.
- 15. Operation within the t_{RAD} (max.) limit insures that t_{RAC} (max.) can be met. t_{RAD} (max.) is specified as a reference point only: If t_{RAD} is greater than the specified t_{RAD} (max.) limit, then access time is controlled by t_{AA}.

READ CYCLE

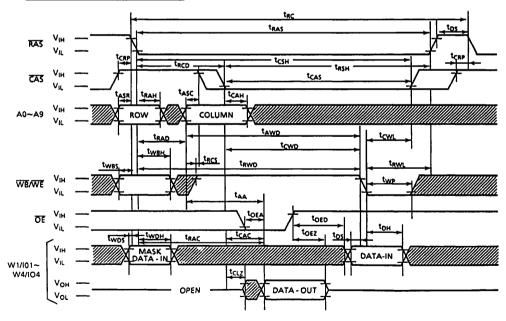


WRITE CYCLE (EARLY WRITE)

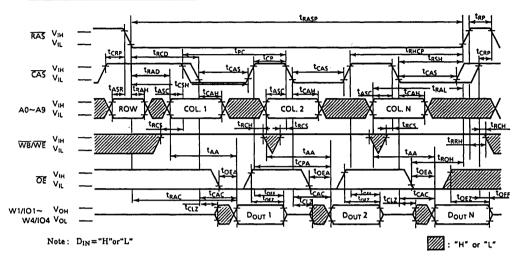




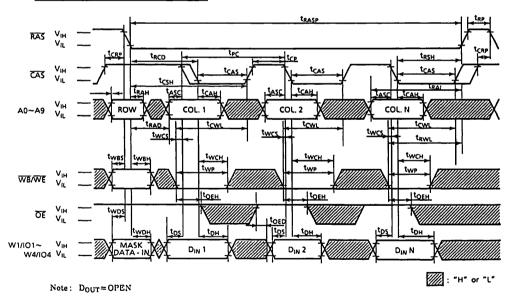
READ - MODIFY - WRITE CYCLE



FAST PAGE MODE READ CYCLE

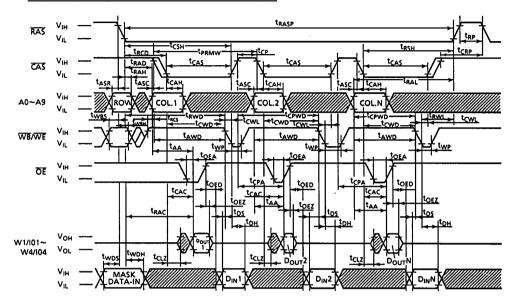


FAST PAGE MODE WRITE CYCLE

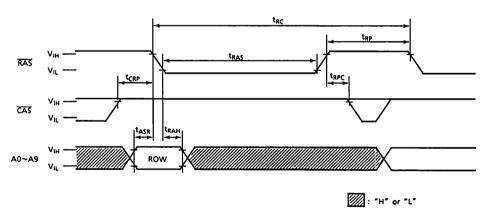


A-519

FAST PAGE MODE READ-MODIFY-WRITE CYCLE

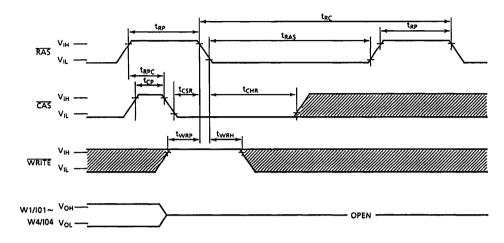


RAS ONLY REFRESH CYCLE



Note: WRITE, OE = "H" or "L"

CAS BEFORE RAS REFRESH CYCLE

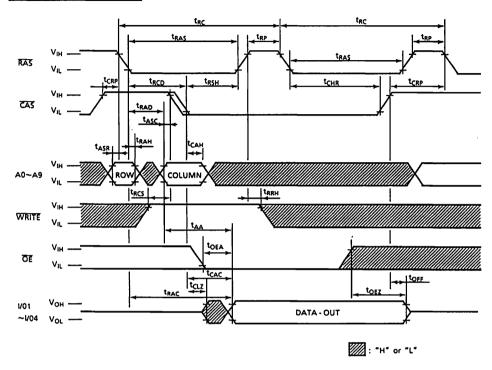


Note: DIN, OE, A0~A9 = "H" or "L"

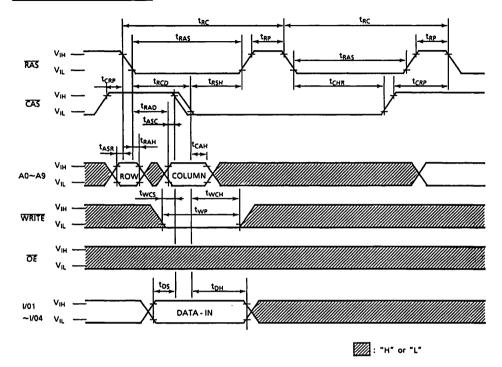
: "H" or "L"



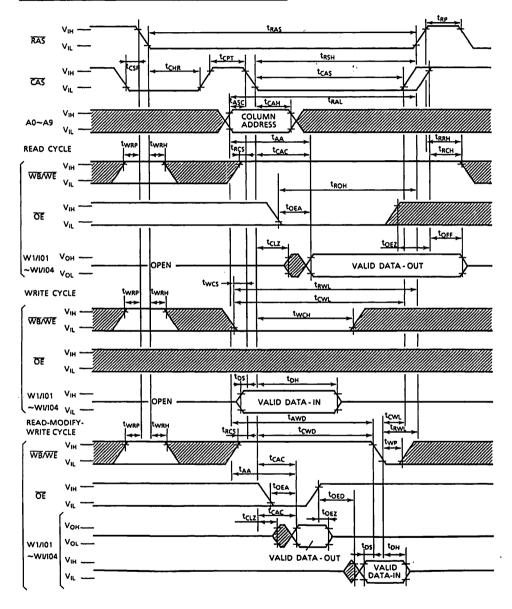
HIDDEN REFRESH CYCLE (READ)



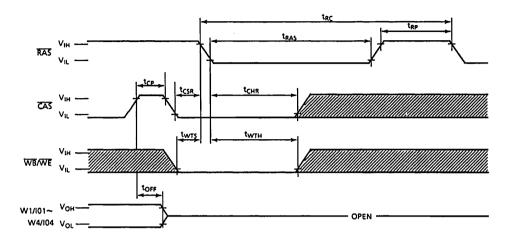
HIDDEN REEFRESH CYCLE (WRITE)



CAS BEFORE RAS REFRESH COUNTER TEST CYCLE



WE, CAS BEFORE RAS REFRESH CYCLE



Note: Din, OE, A0~A9 = "H" or "L"





APPLICATION INFORMATION

ADDRESSING

The 20 address bits required to decode 1 of the 1,048,576 cell locations within the TC51410AP/AJ/ASJ/AZ are multiplexed onto the 10 address inputs and latched into the on-chip address latches by externally applying two negative going TTL-level clocks.

The first clock, the Row Address Strobe (RAS), latches the 10 row address bits into the chip. The second clock, the Column Address Strobe (CAS), subsequently latches the 10 column address bits into the chip. Each of these signals, RAS, and CAS, triggers a sequence of events which are controlled by different delayed internal clocks.

The two clock chains are linked together logically in such a way that the address multiplexing operation is done outside of the critical path timing sequence for read data access. The later events in the $\overline{\text{CAS}}$ clock sequence are inhibited until the occurrence of a delayed signal derived from the $\overline{\text{RAS}}$ clock chain. The "gated $\overline{\text{CAS}}$ " feature allows the $\overline{\text{CAS}}$ clock to be externally activated as soon as the Row Address Hold Time specification (t_{RAH}) has been satisfied and the address inputs have been changed from Row address to Column address information.

DATA INPUTS

A write cycle is performed by bringing (WB/) WE low during the RAS/CAS operation. The falling edge of CAS or (WB/) WE strobes data on (Wi) IOi into the on-chip data latch. To make use of the write-per-bit capability WB(/WE) must be low as RAS falls. In this case data bits to which the write operation is applied can be specified by keeping Wi (/IOi) high with set-up and hold times referenced to the RAS negative transition. For those data bits of Wi (/IOi) that are kept low as RAS talls the write operation is inhibited on the chip if WB(/WE) is high as RAS falls, the write-per-bit capability does not work and the write operation is performed for all four data bits.

DATA OUTPUTS

The three-state output buffers provide direct TTL compatibility with a fan-out of two standard TTL loads. Data-out is the same polarity as data-in. The outputs are in the high-impedance state until CAS is brought low. In a read cycle the outputs go active after the access time interval trac and toea are satisfied.

The outputs become valied after the access time has elapsed and remains valied while CAS and OE are low. CAS or OE going high returns it to a high impedance state. In an early-write cycle, the outputs are always in the high-impedance state. In a delayed-write or read-modify-write cycle, the outputs will follow the sequence for the read cycle.

The OE controls the impedance of the output buffers. In the logic high position the buffers will remain in a high impedance state.

When the \overline{OE} input is brought to a logical low level, the output buffer are enabled. Both \overline{CAS} and \overline{OE} can control the output. Thus in a read operation, either \overline{OE} or \overline{CAS} returning high forces the outputs into the high impedance state.

RAS ONLY REFRESH

Refresh of the dynamic cell matrix is accomplished by performing a memory cycle at each of the 512 row address (A0~A9) within each 16 millisecond time interval.

Although any normal memory cycle will perform the refresh operation, this function is most easily accomplished with "RAS-only" cycles.

CAS BEFORE RAS REFRESH

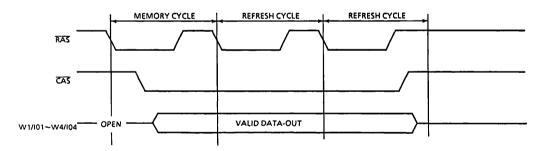
CAS before RAS refreshing available on the TC514410AP/AJ/ASJ/AZ offers an alternate refresh method. If CAS is held on low for the specified period (tCSR) before RAS goes to low, on chip refresh control clock generators and the refresh address counter are enabled, and an internal refresh operation takes place. After the refresh operation is performed, the refresh address counter is automatically incremented in preparation for the next CAS before RAS refresh operation.

PAGE MODE

The "Page-Mode" feature of the TC514410AP/AJ/ASJ/AZ allows for successive memory operations at multiple column locations of the same row address with increased speed without an increase in power. This is done by strobing the row address into the chip and maintaining the RAS signal at a logic 0 throughout all successive memory cycles in which the row address is common. This "Page-Mode" of operation will not dissipate the power associated with the negative going edge of RAS. Also, the time required for strobing in a new address is eliminated, thereby decreasing the access and cycle times.

HIDDEN REFRESH

An optional feature of the TC514410AP/AJ/ASJ/AZ is that refresh cycles may be performed while maintaining valid data at the output pin. This is referred to as Hidden Refresh. Hidden Refresh is performed by holding CAS at V_{IL} and taking RAS high and after a specified precharge period (t_{RP}), executing a CAS before RAS refresh cycle. (see Figure below)



This feature allows a refresh cycle to be "Hidden" among data cycles without affecting the data availability.



CAS BEFORE RAS REFRESH COUNTER TEST

The internal refresh operation of TC514410AP/AJ/ASJ/AZ can be tested by CAS BEFORE RAS REFRESH COUNTER TEST. This cycle performs READ/WRITE operation taking the internal counter address as row address and the input address as column address.

The test is performed after a minimum of 8 CAS before RAS cycles as initialization cycles. The test procedure is as follows.

- ① Write "0" into all the memory cells at normal write mode.
- ② Select one certain column address and read "0" out and write "1" in each cell by performing CAS BEFORE RAS REFRESH COUNTER TEST (READ-WRITE CYCLE). Repeat this operation 512 times.
- 3 Check "1" out of 512 bits at normal read mode, which was written at 2.
- ① Using the same column as ②, read "1" out and write "0" in each cell performing CAS BEFORE RAS REFRESH COUNTER TEST. Repeat this operation 512 times.
- 5 Check "0" out of 512 bits at normal read mode, which was written at 4.
- 6 Perform the above 1 to 5 to the complement data.

TEST MODE

The TC514410AP/AJ/ASJ/AZ is the RAM organized 1,048,576 words by 4 bits, it is internally organized 524,288 words by 8 bits. In "Test Mode", data are written into 8 sectors in parallel and retrieved the same way. A₀₀ is not used. If, upon reading, two bits on one I/O pin are equal (all "1"s or "0"s), the I/O pin indicates a "1". If they were not equal, the I/O pin would indicate a "0". Fig. 1 shows the block diagram of TC514410J/Z. In "Test Mode", the 1M×4 DRAM can be tested as if it were a 512K×4 DRAM.

"WE, CAS Before RAS Refresh Cycle" puts the device into "Test Mode". And "CAS Before RAS Refresh Cycle" or "RAS Only Refresh Cycle" puts it back into "Normal Mode". In the Test Mode, "WE, CAS Before RAS Refresh Cycle" performs the refresh operation with the internal refresh address counter. The "Test Mode" function reduces test times (1/2 in case of N test pattern).

BLOCK DIAGRAM IN THE TEST MODE

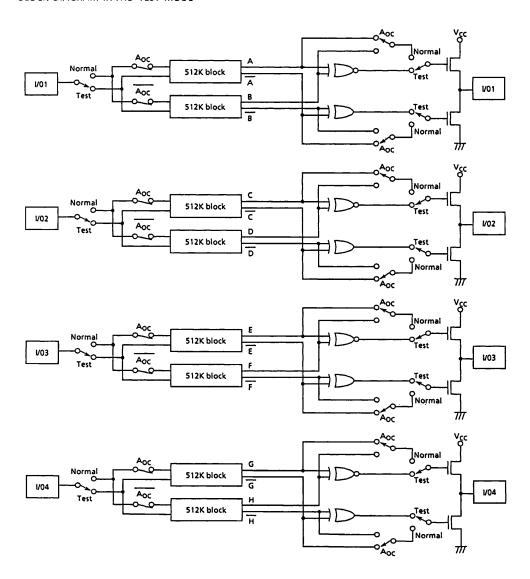


Fig. 1

